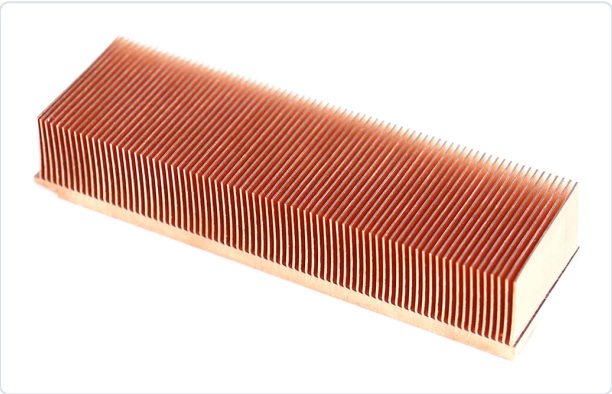


LIQUID COLD PLATE · CPU / PROCESSOR

CPU / Processor Liquid Cold Plate

Custom liquid cold plate — copper c1100 / c1020 construction — for cpu / processor thermal management. Channel layout, material and fluid interface are engineered to the customer platform and validated by CFD.



REFERENCE OPERATING POINT

CPU / Processor cold plate

at specified inlet and flow conditions; final performance confirmed per platform and system-level boundary conditions.

Engineering note: stated figures are design targets — confirmed per platform and system-level boundary conditions.

THERMAL PERFORMANCE

Heat dissipation (ref.) ^{<sup style='color:#c8102e'>1</sup>}	Per application — CFD-validated per project
Thermal resistance	Per T _{case} / surface-temp target — CFD-validated
Cold-plate surface temp.	To customer limit

HYDRAULIC / FLUID

Coolant	DI water / inhibited water-glycol (EGW), per project
Coolant flow rate	Per design
Pressure drop	CFD / test-validated per design
Max operating pressure	Per project

MECHANICAL

Construction	Per design (CNC / brazed / FSW / tube-embedded)
Material	Copper C1100 / C1020
Dimensions	Per customer drawing
Flatness / finish	Per project
Mounting / interface	Per customer interface
Application	CPU / Processor

RELIABILITY, TEST & COMPLIANCE

Leak / pressure test	100% leak / pressure test per project
Inspection	Dimensional + C-scan / ultrasonic for bonded parts
Process	CNC machining, welding, bending, cutting, punching
Compliance	RoHS support on request; CE / REACH documentation on request

Send your platform / module, heat load, coolant, flow rate, inlet temperature & mechanical envelope — ToneCooling returns a CFD-supported design proposal and quotation.